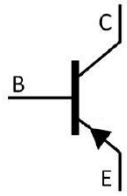
/ Descriptions

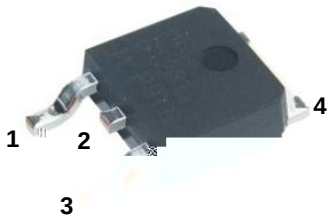
/ Features

/ Applications

/ Equivalent Circuit



/ Pinning



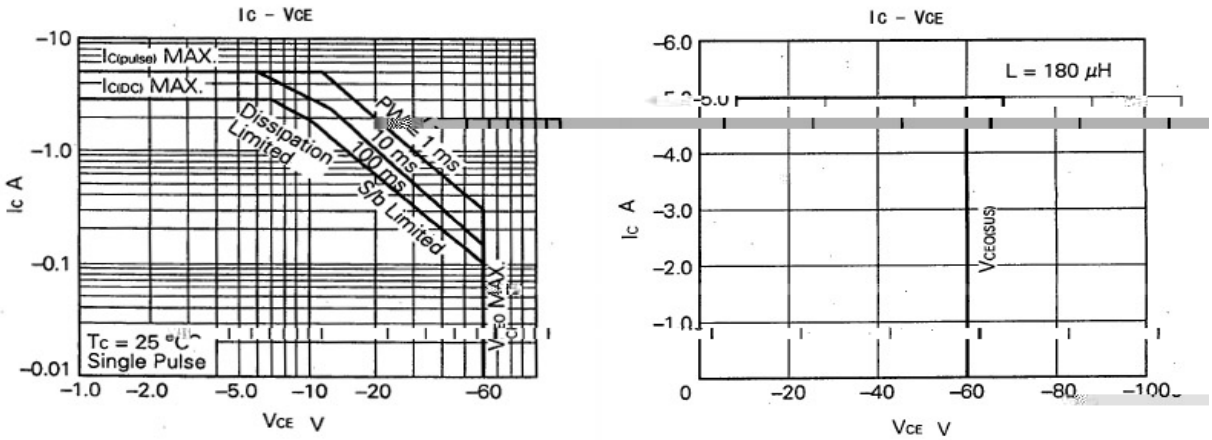
/ h_{FE} Classifications & Marking

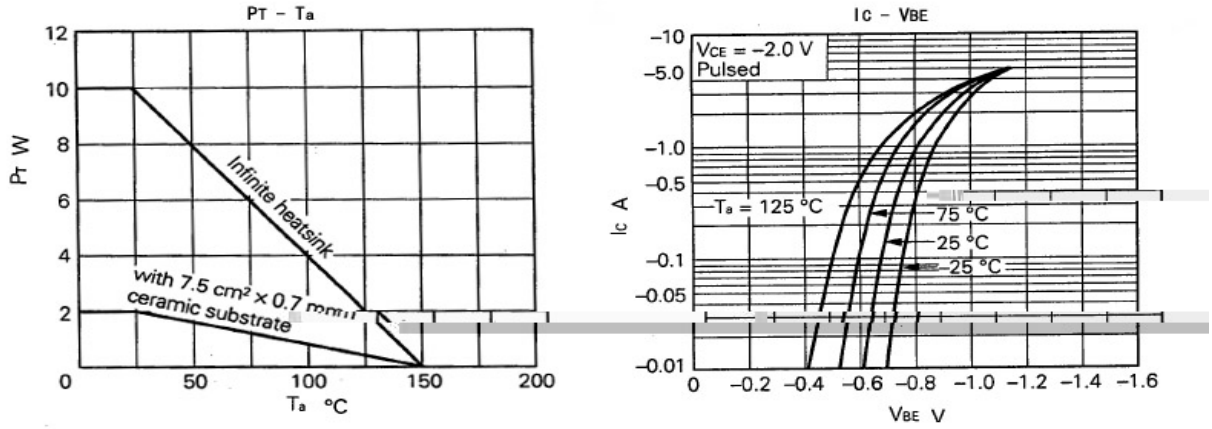
/ Absolute Maximum Ratings(Ta=25)

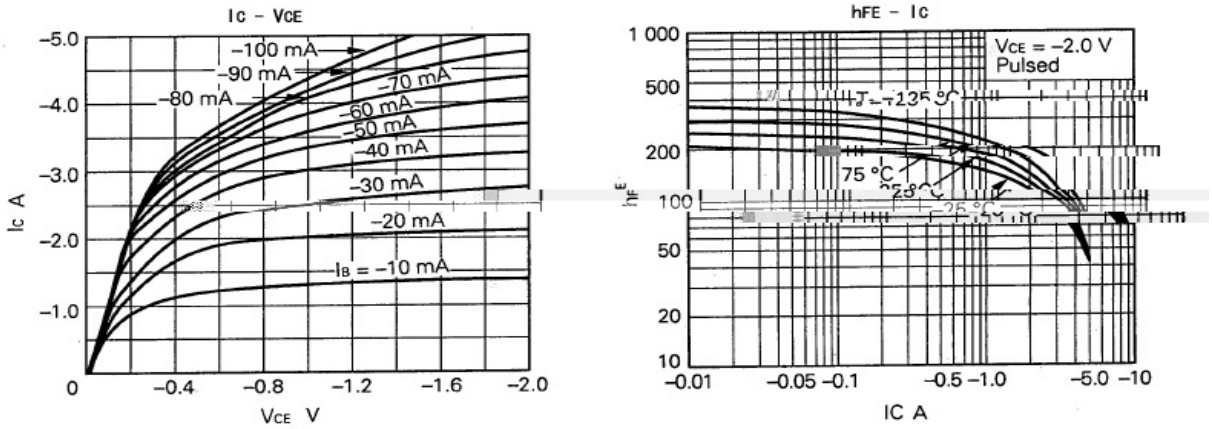
/ Electrical Characteristics(Ta=25)

						μ
						μ
		Ω				

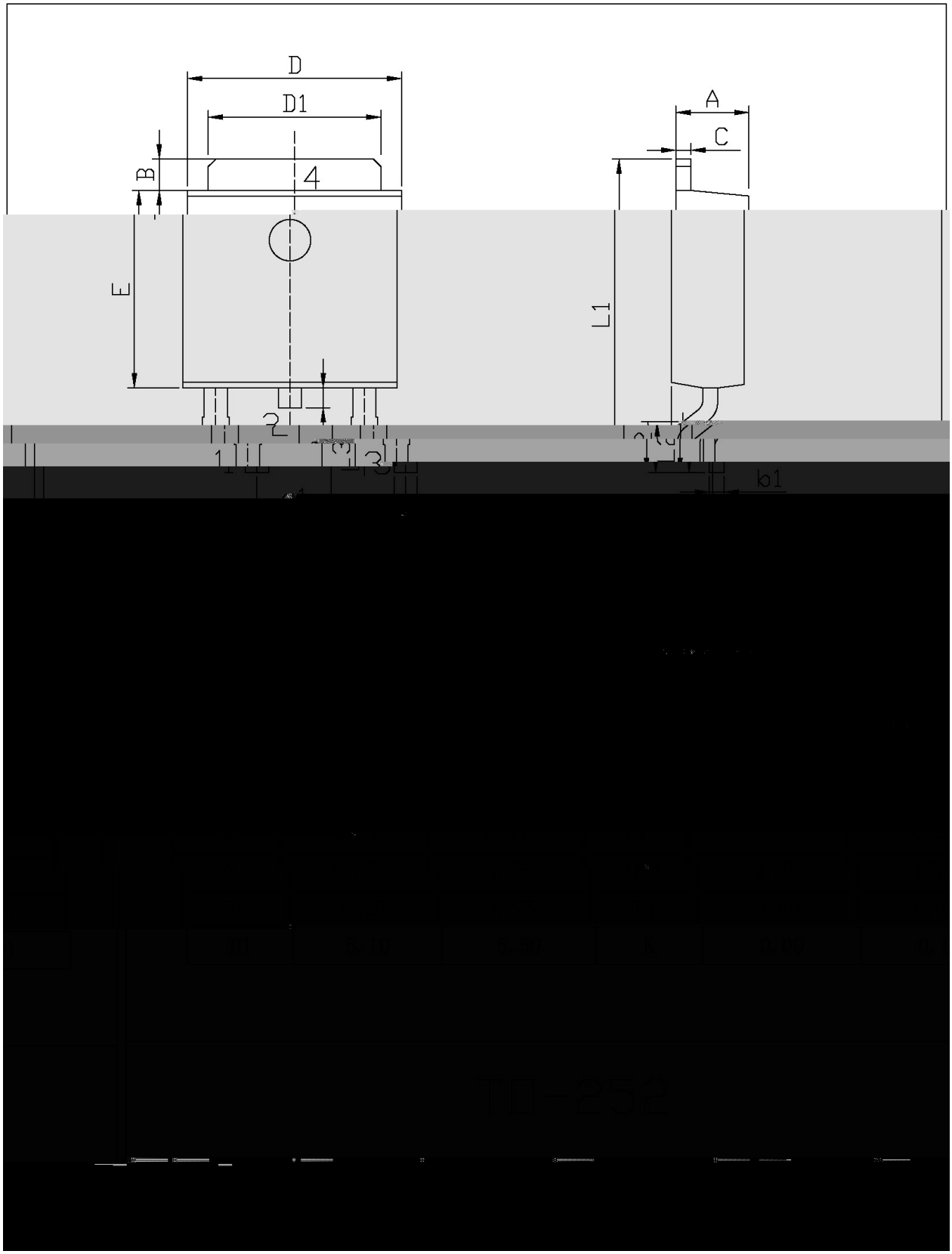
/ Electrical Characteristic Curve



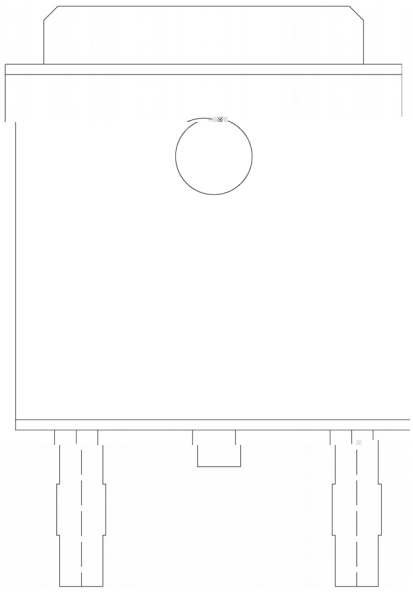




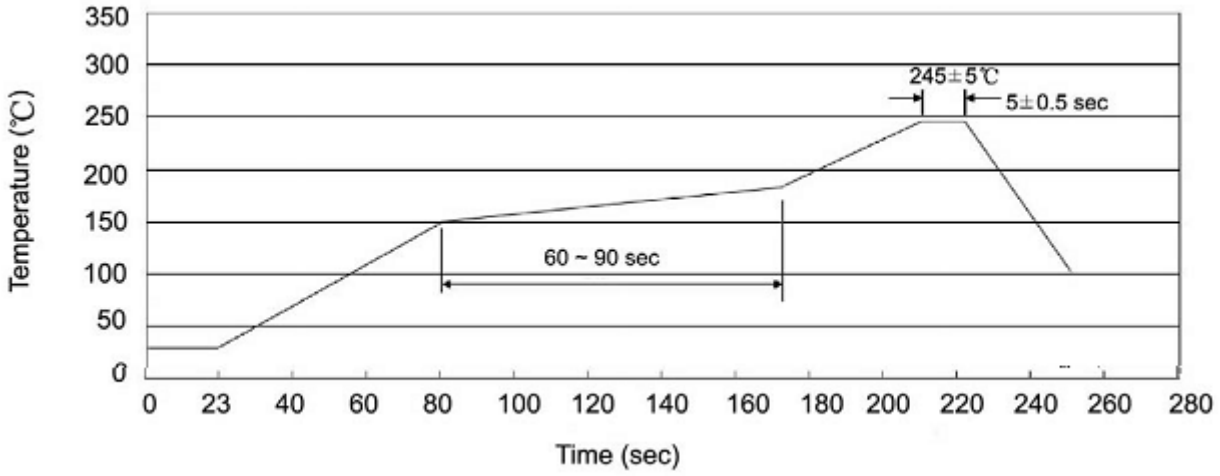
/ Package Dimensions



/ Marking Instructions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

/ Packaging SPEC.

封装形式	包装数量					包装尺寸 :		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

封装形式	包装数量					包装尺寸 :		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices